

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	29/830-852.ccls. and differential near3 trace	USPAT; EPO; JPO	OR	ON	2005/01/04 16:46
L3	25	29/830-852.ccls. and layer near3 trace and power near3 (plane core layer) and dielectric near3 (layer film)	USPAT; EPO; JPO	OR	ON	2005/01/04 16:49
L4	37	174/250-258.ccls. and layer near3 trace and power near3 (plane core layer) and dielectric near3 (layer film)	USPAT; EPO; JPO	OR	ON	2005/01/04 16:51
L5	87	257/691-728.ccls. and layer near3 trace and power near3 (plane core layer) and dielectric near3 (layer film)	USPAT; EPO; JPO	OR	ON	2005/01/04 16:54
L6	40	361/780-795.ccls. and layer near3 trace and power near3 (plane core layer) and dielectric near3 (layer film)	USPAT; EPO; JPO	OR	ON	2005/01/04 16:55
L7	68	"438"/\$.ccls. and layer near3 trace and power near3 (plane core layer) and dielectric near3 (layer film)	USPAT; EPO; JPO	OR	ON	2005/01/04 16:55
S1	6	backplane.ti. and goergen.in.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2004/02/09 18:56
S2	673	multi\$1layer adj circuit with board and laminat\$3 and through adj hole	USPAT; EPO; JPO	OR	ON	2004/02/09 18:57
S3	83	(multi\$1layer adj circuit with board and laminat\$3 and through adj hole) and (copper power signal) adj layer same dielectric	USPAT; EPO; JPO	OR	ON	2004/02/09 18:58
S4	1	"5311406".pn.	USPAT; EPO; JPO	OR	ON	2004/02/09 19:00
S5	64	"29"/\$.ccls. and multi\$1layer with (substrate board) and (dielectric insulat\$3) adj layer and laminat\$4 and power adj (plane layer)	USPAT; EPO; JPO	OR	ON	2004/02/13 15:45
S6	13	(backplane back\$1plane) and multi\$1layer with (substrate board) and (dielectric insulat\$3) adj layer and laminat\$4 and power adj (plane layer)	USPAT; EPO; JPO	OR	ON	2004/02/13 15:48
S7	124	stack\$3 and multi\$1layer with (substrate board) and (dielectric insulat\$3) adj layer and laminat\$4 and power adj (plane layer)	USPAT; EPO; JPO	OR	ON	2004/02/13 15:58